

Circuit Types / Technologies

Single sided & PTH

Multilayer including sequential bonding techniques

Microvia Technology

Blind & Buried Via

High Density Interconnects (HDI)

Controlled Impedance & Differential Matched Pairs

Metal backed, Backplanes & High Frequency

Combination & Special Plated Finishes (HASL/Gold), palladium, cobalt gold & carbon ink.

Depth Milling

Direct Laser Imaging

Flush Bonding

Heavy Copper Weights (>6oz/SqFT)

Thermal Management (Internal/ external heat sinks, thermal risers)

Buried Resistors (Base material and conductive ink formation technologies).

Thin Core Technologies

Flex, Flex-Rigid & Multilayer Flex-Rigid

Hybrid / ceramics